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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10042317	FILING DATE 01/11/2002	CLASS 418 524	SUBCLASS 3	GAU 1714	EXAMINER KEEHAN
**APPLICANTS: Kojima Tosifumi; Takeuchi Hiroki; Obayashi Kazushige;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN P.2001-044795 02/21/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO Q68073	
TITLE : Embedding resin, wiring substrate using same and process for producing wiring substrate using same					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner PREPARED FOR ISSUE Application Examiner	
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